



YL-G1D-E2LJxSD
2W Infrared 850 Power LED
Technical Datasheet
Version: 1.7

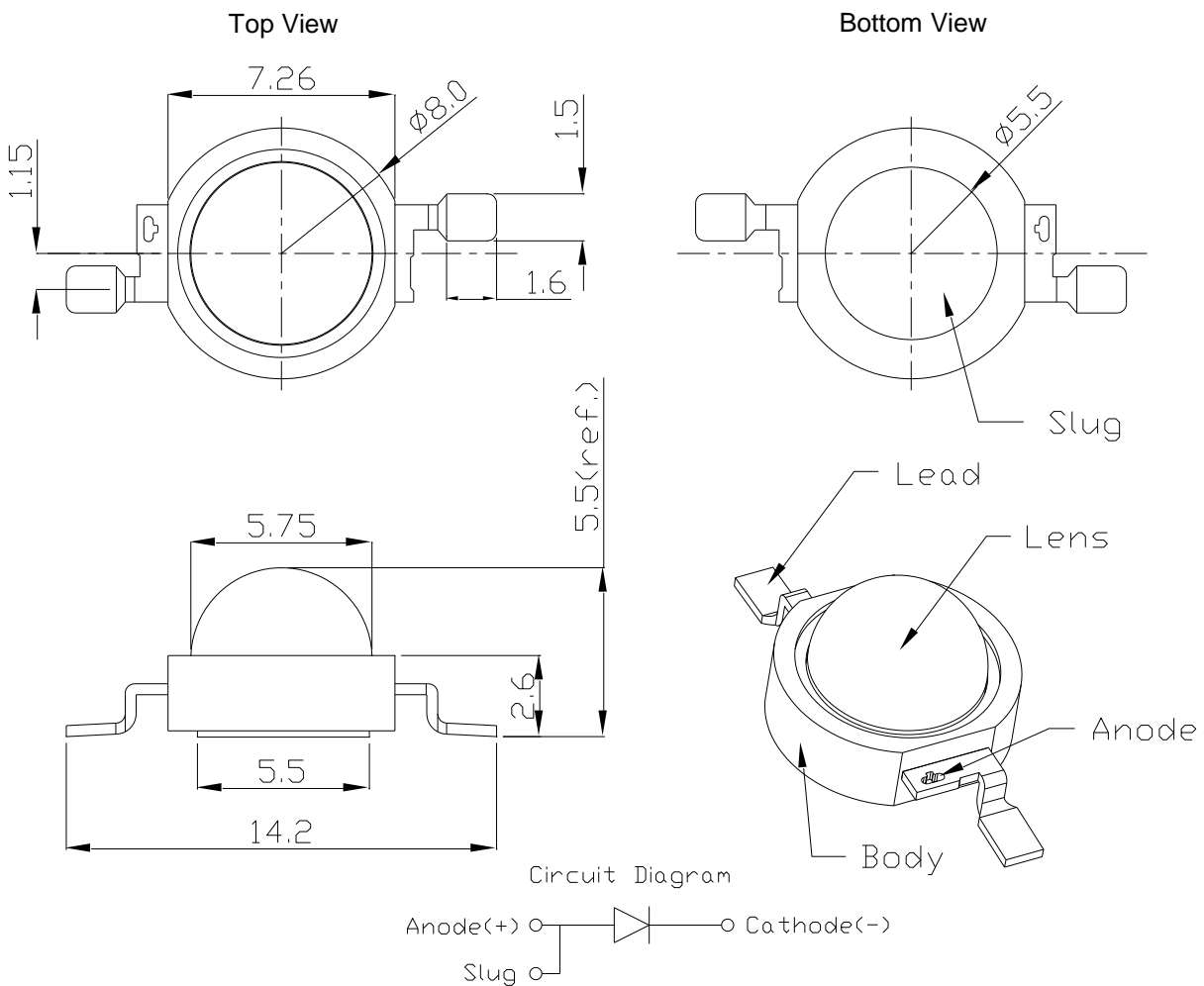
Features

- Industry best moisture sensitivity level - JEDEC Level 1
- Instant light (less than 100ns)
- Lead free reflow soldering
- RoHS compliant
- Cool beam, safe to the touch

Typical Applications

- CCTV
- Wireless communication
- Indoor Lighting
- Outdoor Lighting

Emitter Mechanical Dimensions

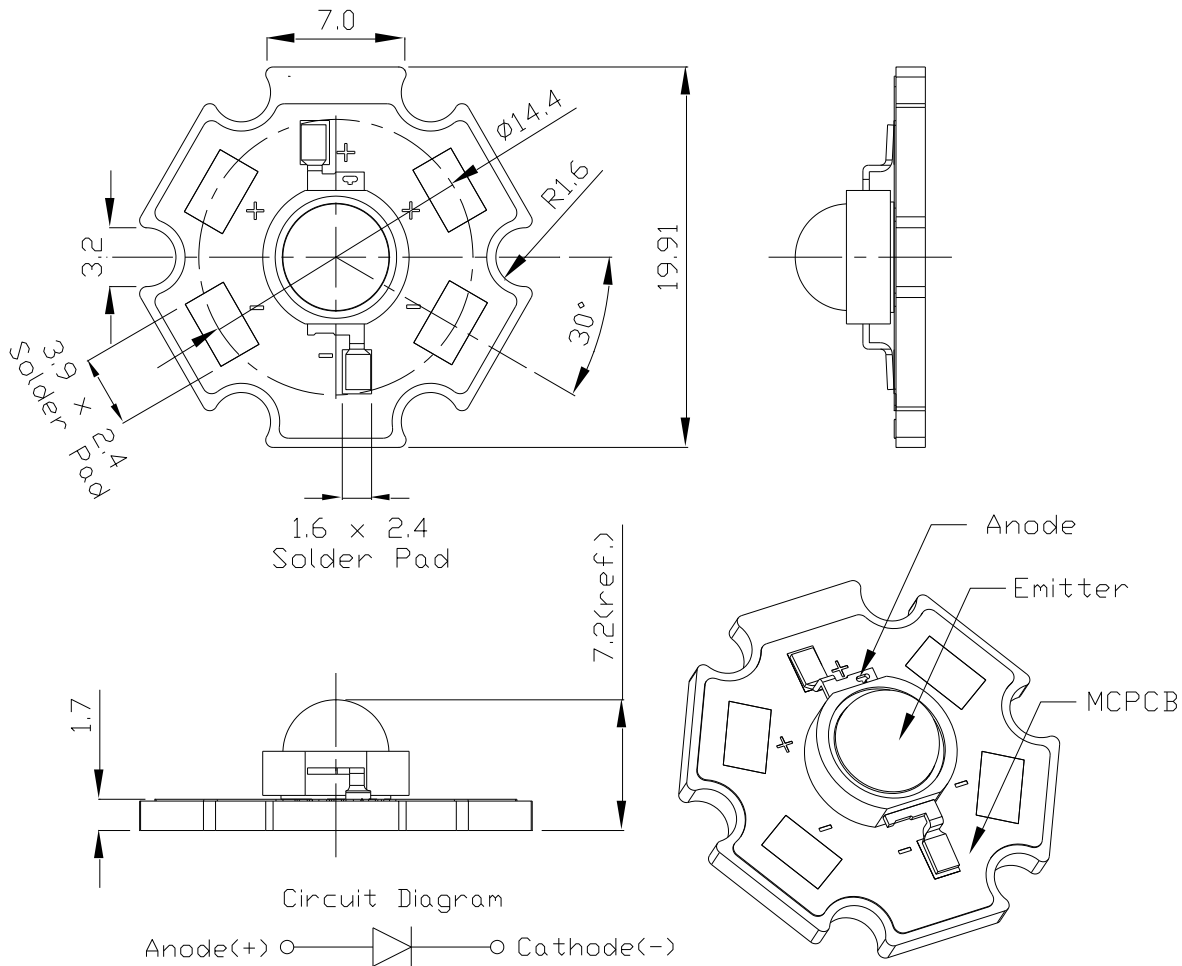


Notes:

1. The Anode side of the device is denoted by a hole in the lead frame.
2. Electrical insulation between the case and the board is required. Do not electrically connect either the anode or cathode to the slug.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. Unless otherwise indicated, tolerances are $\pm 0.20\text{mm}$.
6. Please do not bend the leads of the LED, otherwise it will damage the LED.
7. **Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Star Mechanical Dimensions



Notes:

1. Slots in aluminum-core PCB for M3 or #4 mounting screw.
2. Electrical interconnection pads labeled on the aluminum-core PCB with "+" and "-" to denote positive and negative, respectively. All positive pads are interconnected, as are all negative pads, allowing for flexibility in array interconnection.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. Unless otherwise indicated, tolerances are $\pm 0.20\text{mm}$.
6. **Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 1000mA, T_J = 25°C

Radiation Pattern	Color	Part Number		Radiometric Power (mW)	
		Emitter	Star	Minimum	Typical
Lambertian	Infrared 850	YL-G1D-E2LJESD	YL-G1D-E2LJSSD	635	850

- YesLED maintains a tolerance of ± 7% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 1000mA, T_J = 25°C

Color	Forward Voltage V _F (V)			Thermal Resistance Junction to Slug (°C/ W)
	Min.	Typ.	Max.	
Infrared 850	1.5	1.9	2.3	8

- YesLED maintains a tolerance of ± 0.1V for Voltage measurements.

Optical Characteristics at 1000mA, T_J = 25°C

Color	Min.	Peak Wavelength λ _p		Total included Angle (degrees) θ _{0.90V}	Viewing Angle (degrees) 2 θ _{1/2}
		Typ.	Max.		
Infrared 850	840 nm	855 nm	870 nm	180	130

- YesLED maintains a tolerance of ± 1nm for dominant wavelength measurements.

Absolute Maximum Ratings

Parameter	Infrared 850
DC Forward Current (mA)	1000
Peak Pulsed Forward Current (mA)	1500 (less than 1/10 duty cycle@1KHz)
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)
LED Junction Temperature (°C)	120°C
Operating Board Temperature at Maximum DC Forward Current	-40°C - 90°C
Storage Temperature	-40°C - 120°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

Radiometric Power Bin Structure

Color	Bin Code	Minimum Radiometric Power (mW)	Maximum Radiometric Power (mW)	Available Color Bins
Infrared 850	S	635	755	All
	T	755	875	All
	U	875	1050	[1]

- YesLED maintains a tolerance of ± 7% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- ^[1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Peak Wavelength Bin Structure

Color	Bin Code	Minimum Peak Wavelength (nm)	Maximum Peak Wavelength (nm)
Infrared 850	1	840	870

- YesLED maintains a tolerance of ± 1nm for peak wavelength measurements.

Forward Voltage Bin Structure

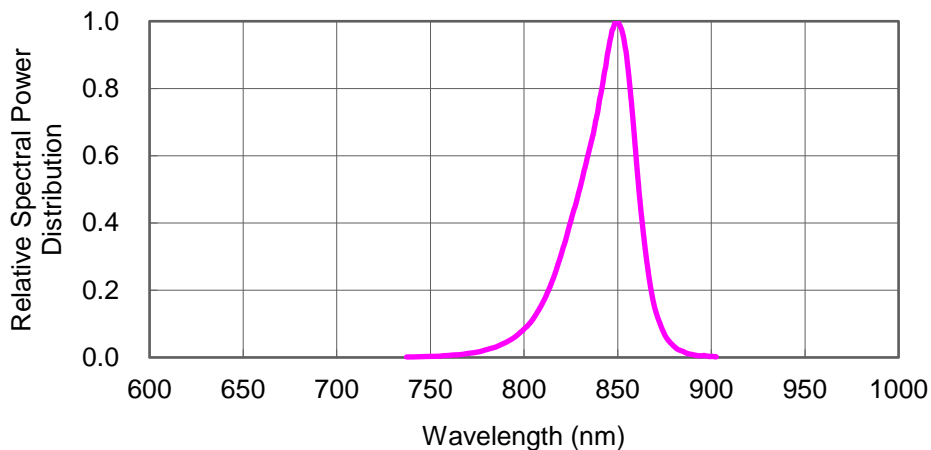
Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
Infrared 850	E	1.5	1.6
	F	1.6	1.7
	G	1.7	1.8
	H	1.8	1.9
	J	1.9	2.0
	K	2.0	2.1
	L	2.1	2.2
M	2.2	2.3	

- YesLED maintains a tolerance of ± 0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

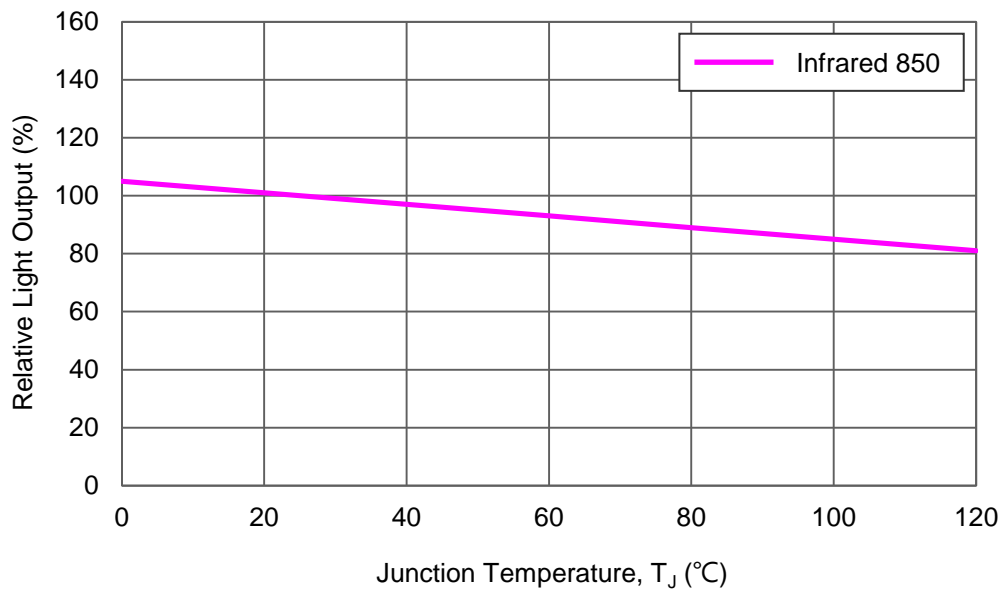
Color Spectrum, $T_J = 25^\circ\text{C}$

1. Infrared 850



Light Output Characteristics

Relative Light Output vs. Junction Temperature at 1000mA



Forward Current Characteristics, $T_J = 25^\circ\text{C}$

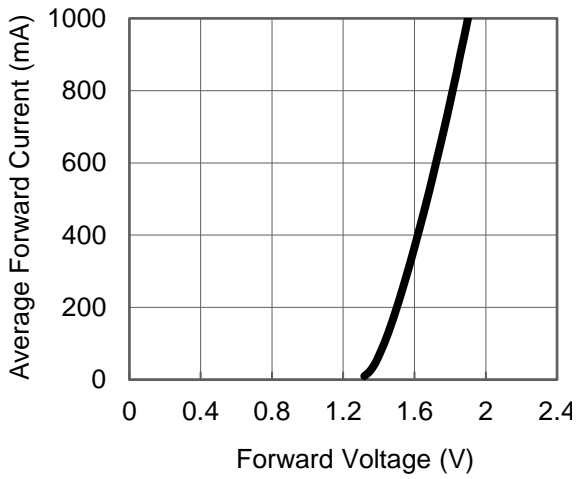


Fig 1. Forward Current vs. Forward Voltage for Infrared 850.

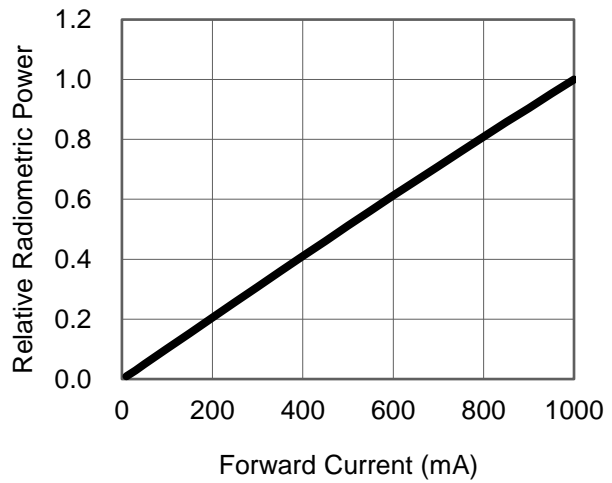
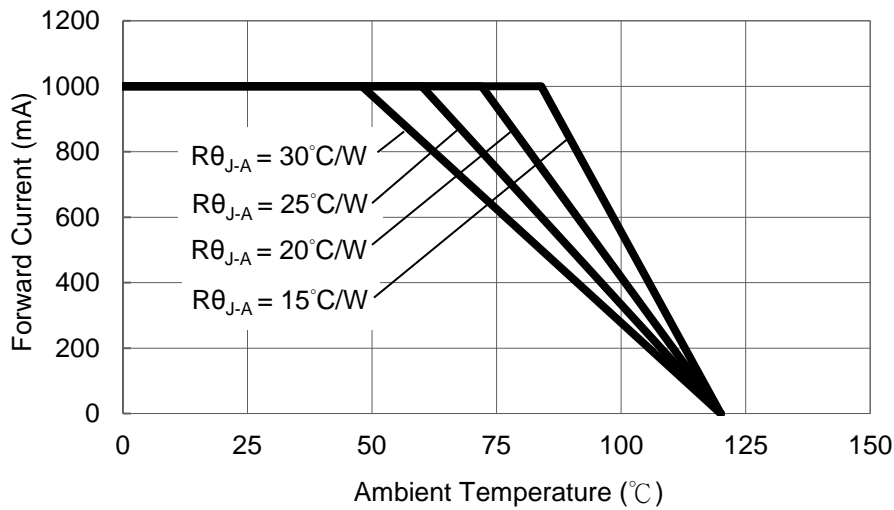


Fig 2. Relative Radiometric Power vs. Forward Current for Infrared 850 at $T_J=25^\circ\text{C}$ maintained.

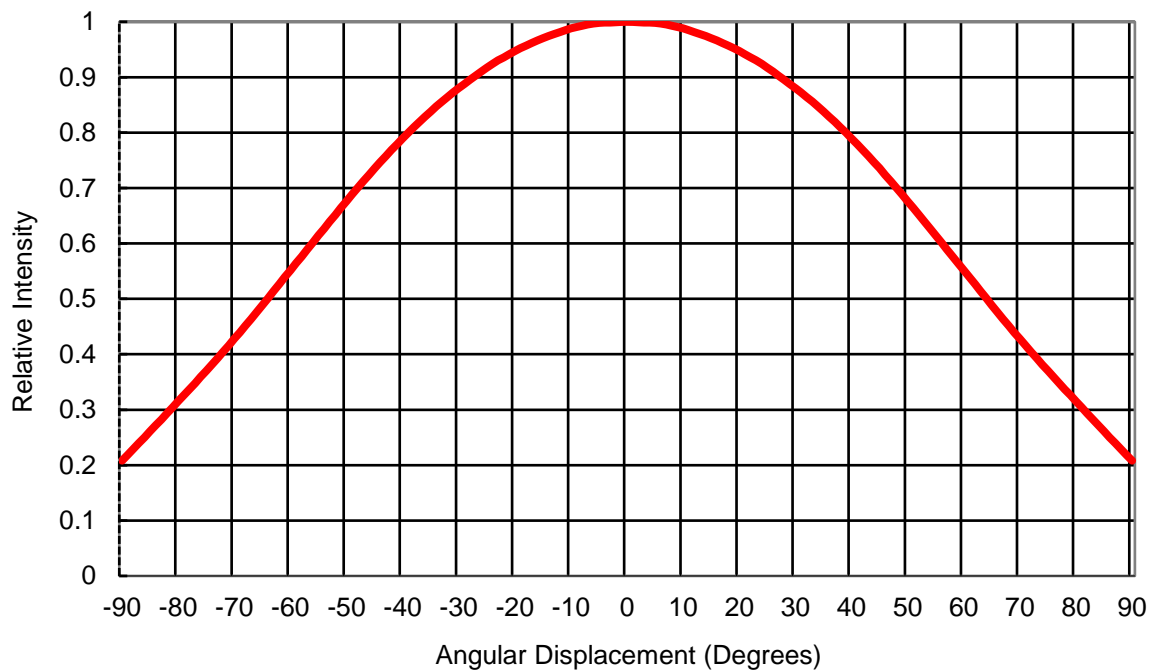
Ambient Temperature vs. Maximum Forward Current

1. Infrared 850 ($T_{JMAX} = 120^\circ\text{C}$)



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Moisture Sensitivity Level - JEDEC Level 1

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufacture's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, $I_F = \text{max DC}$ (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, $I_F = \text{max DC}$ (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

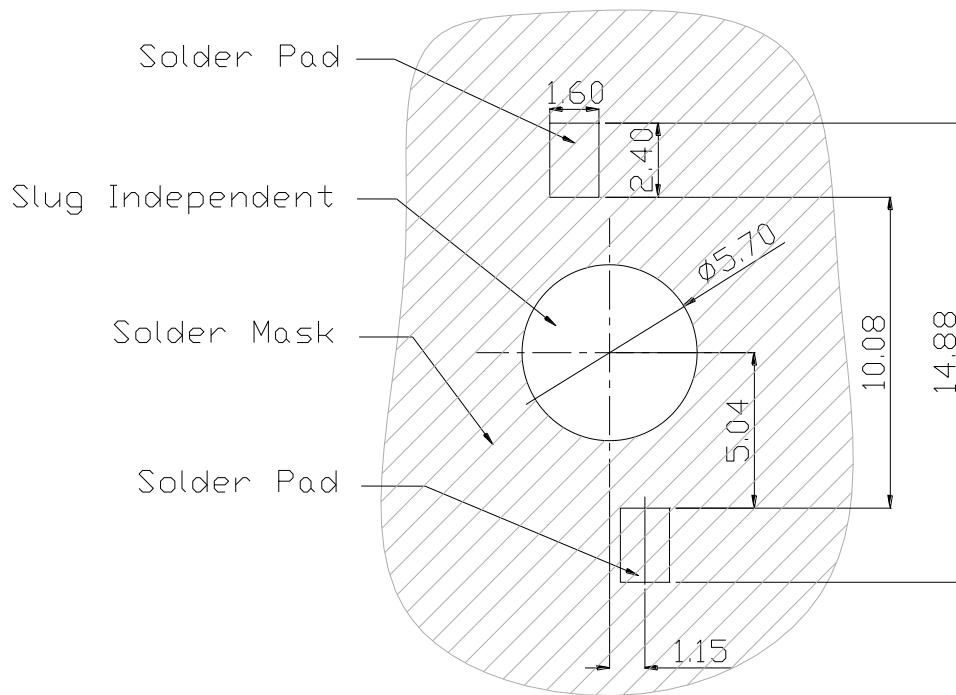
1. Depending on the maximum derating curve.
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	$I_F = \text{max DC}$	-	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	$I_F = \text{max DC}$	Initial Level x 0.7	-

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

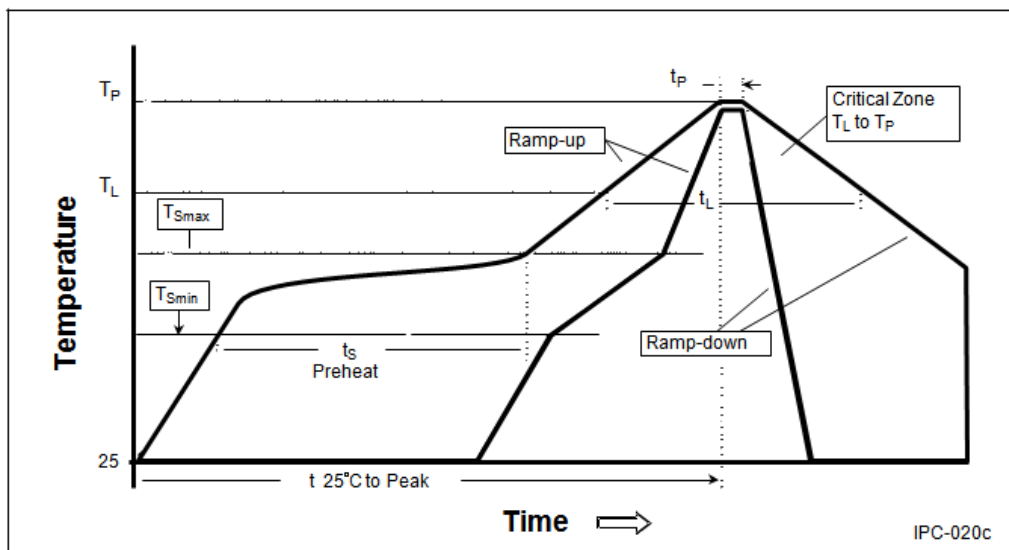
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

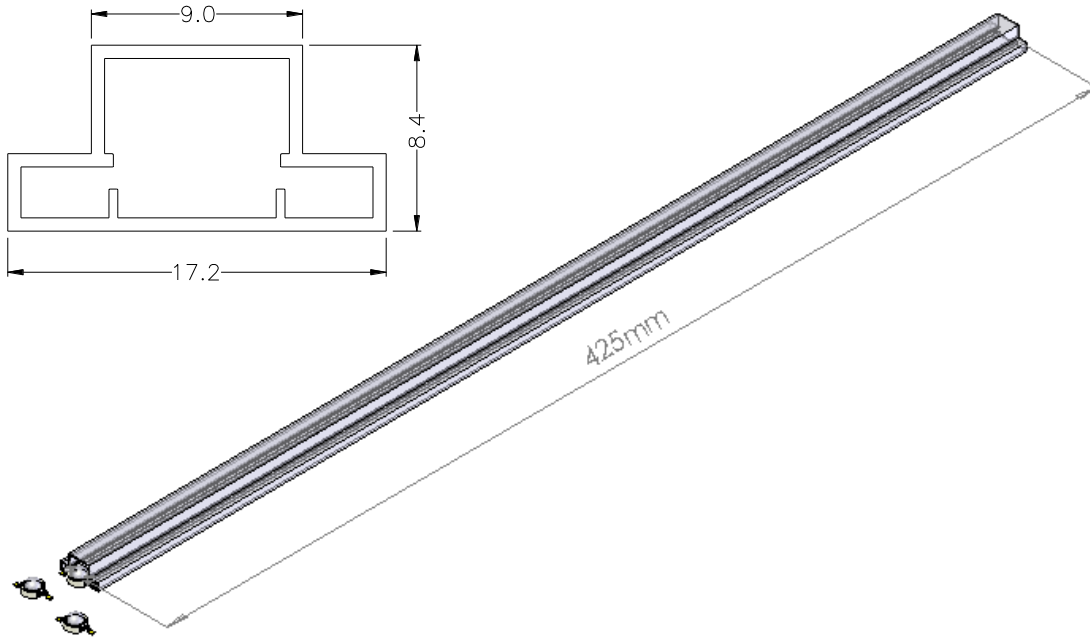
Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_P)	3°C / second max.	3°C / second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{Smin}) - Temperature Max (T_{Smax}) - Time (t_{Smin} to t_{Smax}) 	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (T_P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

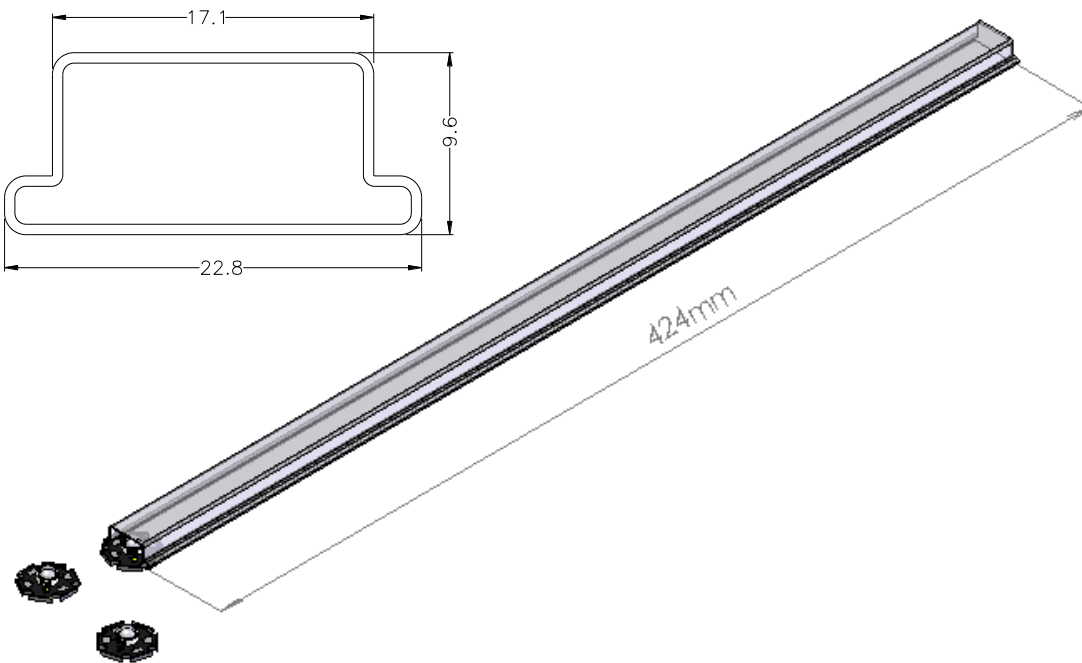


- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Tube Packaging



Star Tube Packaging



Notes:

1. Emitter 50 pieces per tube and Star 20 pieces per tube.
2. Drawing not to scale.
3. All dimensions are in millimeters.
4. All dimensions without tolerances are for reference only.

**Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing YesLED's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

- Storage
Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing YesLED's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30 °C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The LEDs are sensitive to electrostatic discharge. Appropriate ESD protection measures must be taken when working with the LEDs. Non-compliance with ESD protection measures may lead to damage or destruction of the LEDs.
- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets.